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OK International Launches New APR-5000-DZ Array Package Rework System with Dual Convection Bottom-side Heating for lead-free rework and high thermal demand applications

Latest APR-5000-DZ Array Package Rework System enhances and enables fast ramp and tighter delta temperature control for lead-free rework without affecting adjacent and underside components; system expands capability to rework odd-form and temperature sensitive components; intuitive software and user prompts simplify training and provide repeatable process control.



OK International is introducing the new APR-5000-DZ Array Package Rework System for BGA and SMT rework. This latest addition to the company's comprehensive APR-5000 Series delivers highly targeted and controlled heating for rework of high thermal demand boards including lead-free and multi-layer assemblies up to 12" x 12" (305mm x 305mm).

The APR-5000-DZ system has a US-patented, dual convection bottom-side heater that enables faster rework while controlling the temperature to levels required by component and material manufacturers' specifications. The dual convection heater consists of both a large area and small area (localized) heaters. In concert with the top-side convection heater, faster heating rates with small temperature deltas are achieved during rework. Additionally, the proprietary nozzle design serves to protect components directly adjacent to the rework zone as well as other temperature-sensitive devices on the board.

The APR-5000-DZ provides users with the capability to rework components with a 0.4 mm pitch. Additionally, new nozzle technology enables the system to rework components where vacuum pick-up is not an option. In addition to BGA and CSP, odd-form components including through-hole parts, connectors, potentiometers, sockets, and even package-on-package (PoP) devices, can be removed and placed effectively and consistently.

The APR-5000-DZ supports the rework process with precision alignment control and an integrated vision system. A unique, new strobe light facilitates viewing the dual image of both component and board. The APR-5000-DZ includes an industrial PC with operating system and application software, LCD monitor, keyboard and mouse for rework. Its application software provides the user with highly intuitive, easy to use profiling tools. Once profiles are established they can be saved. Operators are seamlessly “coached” with the software’s user prompts. The APR system software can call up a profile and contains step-by-step instructions that quickly detail the action required for rework. The profiles can also be shared across multiple APR-5000-DZ systems with cross-system repeatability to 5°C.

The system is ideal for small, high density boards used in such products as mobile phones, handheld instruments and personal media players. The APR Series of rework systems also includes the APR-5000-XLS for rework of boards up to 24” x 24” (610 x 610 mm). These systems are a popular and fast growing choice for advanced package rework and are supported world-wide by experienced applications and service expertise.

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About OK International

OK International is a leading global supplier of soldering tools and equipment for electronics assembly. The product range includes bench top soldering and desoldering tools, array package rework equipment, fluid dispensing systems and accessories, and fume extraction systems.

OK International is committed to understanding the product needs of its customers and supplies professional grade products that are innovative, reliable, price competitive and easy to use. Through a global sales channel, OK International provides expert product support and responsive customer service, with localisation to meet regional market needs.